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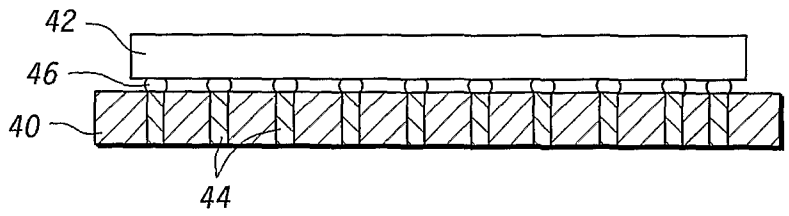
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(54) **Title:** METHOD OF MAKING REINFORCED SEMICONDUCTOR PACKAGE



(57) **Abstract:** A method of making a reinforced semiconductor package includes forming a semiconductor interconnect tablet (24). Formation of the tablet includes providing a plurality of conductive metal tabs (10), positioning a first end (12) of the tabs (10) in a first section of a mold chase (14), positioning a second section of the mold chase (16) over a second end (18) of the tabs (10), such that the tabs (10) are anchored between the first and second sections (14, 16) of the mold chase, loading the first and second sections (14, 16) of the mold chase into a molding system (20) and performing a molding operation such that a plastic mold compound (22) is formed around the metal tabs (10) and an interconnect tablet (24) is formed. Then the first and second sections (14, 16) of the mold chase are removed from the molding system (20) and the interconnect tablet (24) is removed from the first and second sections (14, 16) of the mold chase.

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